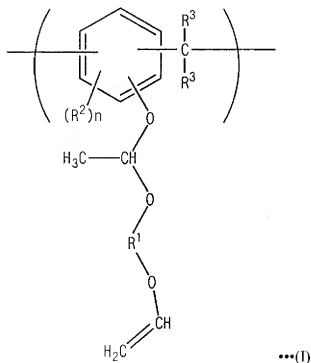


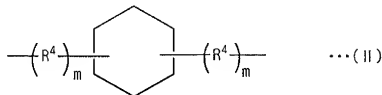
AMENDMENTS TO THE CLAIMS

1. (Currently amended) A chemical amplification type positive photoresist composition prepared by dissolving:

(A) a slightly alkali-soluble or alkali-insoluble novolak resin having a property that solubility in an aqueous alkali solution is enhanced in the presence of an acid, comprising either or both of a constituent unit (a1) represented by the following general formula (I):

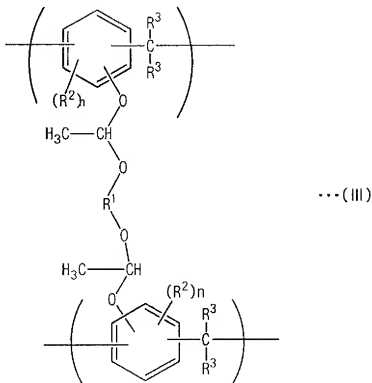


wherein R¹ represents either an alkylene group having 1 to 10 carbon atoms which may have a substituent or a group represented by the following general formula (II):



(wherein R⁴ represents an alkylene group having 1 to 10 carbon atoms which may have a substituent and m represents 0 or 1), the alkylene group may have an oxygen bond (ether bond) in the main chain, R² and R³ each independently represents a hydrogen atom or an alkyl group

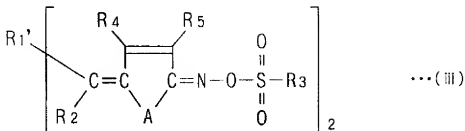
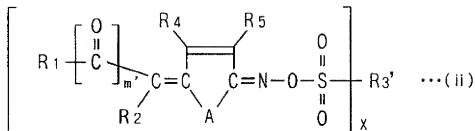
having 1 to 3 carbon atoms, and n represents an integer of 1 to 3, and an intermolecular crosslinked moiety (a2) represented by the following general formula (III):



wherein R^1 represents either an alkylene group having 1 to 10 carbon atoms which may have a substituent or a group represented by the above general formula (II) (wherein R^4 represents an alkylene group having 1 to 10 carbon atoms which may have a substituent and m represents 0 or 1), the alkylene group may have an oxygen bond (ether bond) in the main chain, R^2 and R^3 each independently represents hydrogen atom or alkyl group having 1 to 3 carbon atoms, and n represents an integer of 1 to 3; and

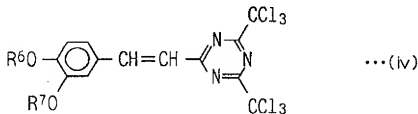
(B) a compound generating an acid under irradiation, wherein said

compound is represented by the following general formulas (ii) and (iii):



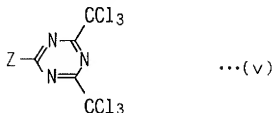
wherein m' represents 0 or 1; X represents 1 or 2; R_1 represents a phenyl group which may be substituted with one or more alkyl groups having 1 to 12 carbon atoms, a heteroaryl group, or an alkoxy carbonyl group having 2 to 6 carbon atoms, a phenoxy carbonyl group or CN when m' is 0; R_1' represents an alkylene group having 2 to 12 carbon atoms; R_2 represents a phenyl group which may be substituted with one or more alkyl groups having 1 to 12 carbon atoms, a heteroaryl group, or an alkoxy carbonyl group having 2 to 6 carbon atoms, phenoxy carbonyl group or CN when m' is 0; R_3 represents an alkyl group having 1 to 18 carbon atoms; R_3' represents an alkyl group having 1 to 18 carbon atoms when $X = 1$, or an alkylene group having 2 to 12 carbon atoms or a phenylene group when $X = 2$; R_4 and R_5 each independently represents a hydrogen atom, halogen, or an alkyl group having 1 to 6 carbon atoms; A represents S, O or NR_6 ; and R_6 represents a hydrogen atom or a phenyl group.

a bis(trichloromethyl)triazine compound represented by the following formula (iv):



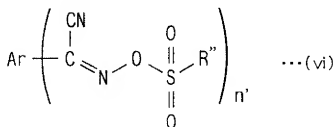
wherein R^6 and R^7 each represents alkyl group having 1 to 3 carbon atoms.

a combination of the compound (iv) and a bis(trichloromethyl)triazine compound represented by the following formula (v):



wherein Z represents a 4-alkoxyphenyl group, or

a compound represented by the following formula (vi):



wherein Ar represents a substituted or unsubstituted phenyl group or a naphthyl group; R'' represents an alkyl group having 1 to 9 carbon atoms; and n' represents an integer of 2 or 3, in an organic solvent,

wherein the content of an acid component in the photoresist composition is 10 ppm or less.

2. (Canceled)

3. (Canceled)

4. (Previously presented) The chemical amplification type positive photoresist composition according to claim 1, wherein the component (B) is a compound generating an acid under irradiation with i-rays (365 nm).

5. (Previously presented) The chemical amplification type positive photoresist composition according to claim 1, which further comprises a basic compound as the component (C).

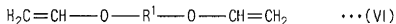
6. **(Original)** The chemical amplification type positive photoresist composition according to claim 5, which comprises the component (C) in the amount of 0.01 to 5 parts by weight based on 100 parts by weight of the resin component contained in the resist composition.

7. **(Previously presented)** The chemical amplification type positive photoresist composition according to claim 1, which comprises γ -butyrolactone.

8. **(Previously presented)** The chemical amplification type positive photoresist composition according to claim 1, which is used for a thick-film photolithography process used for forming a resist film having a thickness of about 2 to 7 μm .

9. **(Original)** The chemical amplification type positive photoresist composition according to claim 8, wherein the thick-film photolithography process is used for forming a resist pattern for implantation.

10. **(Currently amended)** ~~A method for synthesis of the component (A) of claim 1, which comprises~~ The chemical amplification type positive photoresist composition according to claim 1, wherein the component (A) is made by reacting the novolak resin with a crosslinking agent represented by the following general formula (VI):



wherein R^1 represents either an alkylene group having 1 to 10 carbon atoms which may have a substituent or a group represented by the above general formula (II) (wherein R^4 represents an alkylene group having 1 to 10 carbon atoms which may have a substituent and m represents 0 or 1, and the alkylene group may have an oxygen bond (ether bond) in the main chain, in the substantial absence of an acid catalyst.

11. **(Canceled)**

12. **(Canceled)**

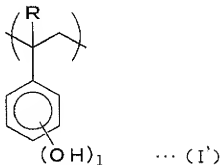
13. **(Previously presented)** A method for formation of a resist pattern of a thick-film photolithography process, which comprises forming a resist film having a thickness of 2 to 7 μm

made of the chemical amplification type positive resist composition of claim 1 on a substrate, and subjecting to selective exposure, post exposure bake (PEB) treatment, and development.

14. **(Original)** The method for formation of a resist pattern according to claim 13, wherein a resist pattern for implantation is formed in the thick-film photolithography process.

15. **(Previously presented)** A chemical amplification type positive photoresist composition comprising (A2) a resin made of a reaction product of (A1) an alkali soluble resin and (C1) a crosslinking polyvinyl ether compound wherein alkali solubility enhances by an action of an acid, and (B1) a photo acid generator generating acid under irradiation with radiation, wherein

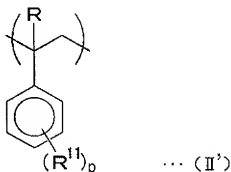
the component (A1) comprises a unit (a1') derived from (α -methyl)hydroxystyrene represented by the following general formula (I'):



wherein R represents a hydrogen atom or a methyl group and 1 represents an integer of 1 to 3, and an alkali-insoluble unit (a2') having no acid dissociable dissolution inhibiting group, and wherein a dissolution rate of the component (A1) to an aqueous 2.38% by weight solution of TMAH (tetramethylammonium hydroxide) is from 10 to 100 nm/second,

wherein the component (B1) is a poly(bissulfonyl)diazomethane photo acid generator.

16. **(Original)** The chemical amplification type positive photoresist composition according to claim 15, wherein the constituent unit (a2') is a unit derived from (α -methyl)styrene represented by the following general formula (II'):



wherein R represents a hydrogen atom or a methyl group, R^{11} represents an alkyl group having 1 to 5 carbon atoms and p represents an integer of 0 or 1 to 3.

17. **(Original)** The chemical amplification type positive photoresist composition according to claim 16, wherein the content of constituent unit (a2') in the component (A1) is from 5 to 35 mol%.

18. **(Original)** The chemical amplification type positive photoresist composition according to claim 15, wherein the weight-average molecular weight of the component (A2) is from 20000 to 150000.

19. **(Canceled)**

20. **(Canceled)**

21. **(Original)** The chemical amplification type positive photoresist composition according to claim 15, which further comprises a nitrogen-containing organic compound (D').

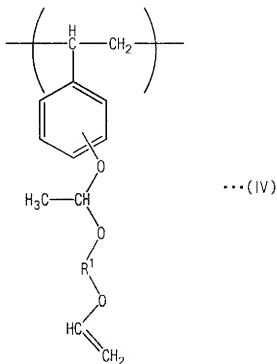
22. **(Original)** A resist pattern forming method, which comprises applying the chemical amplification type positive photoresist composition of claim 15 on a substrate, and subjecting to prebaking, selective exposure, PEB (post exposure bake) and alkali development to form a resist pattern.

23-29. **(Canceled)**

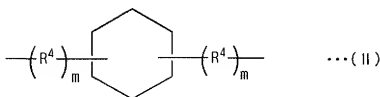
30. **(Currently amended)** A method for formation of a resist pattern of a thick-film photolithography process, which comprises forming a resist film having a thickness of 2 to 7 μm

made of a chemical amplification type positive resist composition on a substrate, wherein said chemical amplification type positive photoresist composition is prepared by dissolving:

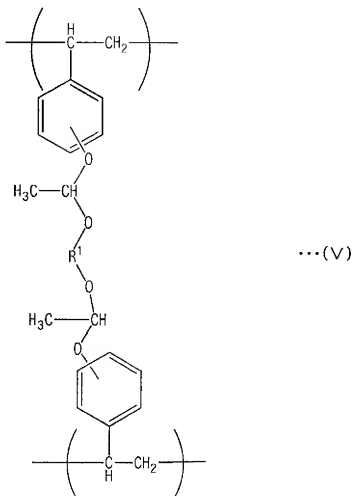
(A') a slightly alkali-soluble or alkali-insoluble polyhydroxystyrenic resin having a property that solubility in an aqueous alkali solution is enhanced in the presence of an acid, comprising either or both of a constituent unit (a'1) represented by the following general formula (IV):



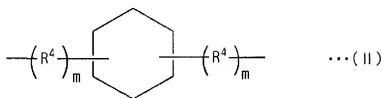
wherein R¹ represents either an alkylene group having 1 to 10 carbon atoms which may have a substituent or a group represented by the following general formula (II):



(wherein R^4 represents an alkylene group having 1 to 10 carbon atoms which may have a substituent and m represents 0 or 1), the alkylene group may have a oxygen bond (ether bond) in the main chain, and an intermolecular crosslinked moiety ($a'2$) represented by the following general formula (V):



wherein R^1 represents either an alkylene group having 1 to 10 carbon atoms which may have a substituent or a group represented by the following general formula (II):



(wherein R^4 represents an alkylene group having 1 to 10 carbon atoms which may have a substituent and m represents 0 or 1), the alkylene group may have an oxygen bond (ether bond) in the main chain; and

(B) ~~a compound generating an acid under irradiation~~ poly(bissulfonyl)diazomethane photoacid generator in an organic solvent,

wherein the content of an acid component in the entire photoresist composition is 10 ppm or less;

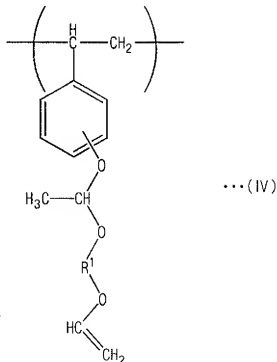
and subjecting to selective exposure, post exposure bake (PEB) treatment, and development.

31. **(Previously presented)** The method for formation of a resist pattern according to claim 30, wherein a resist pattern for implantation is formed in the thick-film photolithography process.

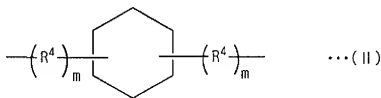
32-38. **(Canceled)**

39. **(Currently amended)** A method for formation of a resist pattern of a thick-film photolithography process, which comprises forming a resist film having a thickness of 2 to 7 μm made of a chemical amplification type positive resist composition on a substrate, wherein said chemical amplification type positive photoresist composition is prepared by dissolving:

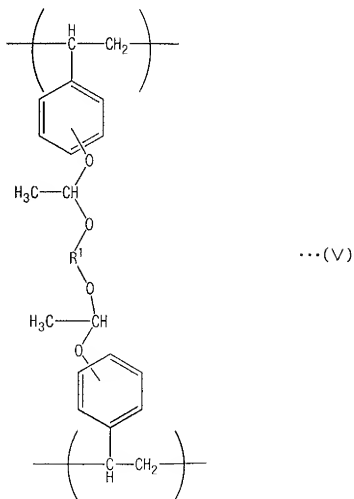
(A'') a slightly alkali-soluble or alkali-insoluble polyhydroxystyrenic resin having such a property that solubility in an aqueous alkali solution is enhanced in the presence of an acid comprising either or both of a constituent unit (a'1) represented by the following general formula (IV):



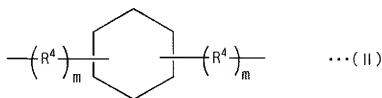
wherein R^1 represents either an alkylene group having 1 to 10 carbon atoms which may have a substituent or a group represented by the following general formula (II):



(wherein R^4 represents an alkylene group having 1 to 10 carbon atoms which may have a substituent and m represents 0 or 1), the alkylene group may have an oxygen bond (ether bond) in the main chain, and an intermolecular crosslinked moiety ($\text{a}'2$) represented by the following general formula (V):



wherein R¹ represents either an alkylene group having 1 to 10 carbon atoms which may have a substituent or a group represented by the following general formula (II):



(wherein R^4 represents an alkylene group having 1 to 10 carbon atoms which may have a substituent and m represents 0 or 1), the alkylene group may have an oxygen bond (ether bond) in the main chain, and a styrenic constituent unit; and

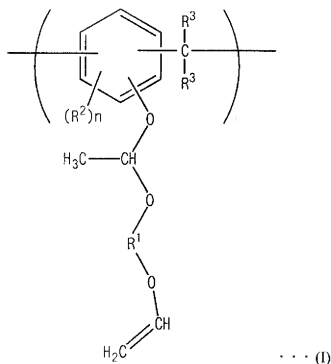
(B) ~~a compound generating an acid under irradiation~~ poly(bissulfonyl)diazomethane photoacid generator in an organic solvent, wherein the content of an acid component in the entire photoresist composition is 10 ppm or less; and subjecting to selective exposure, post exposure bake (PEB) treatment, and development.

40. **(Previously presented)** The method for formation of a resist pattern according to claim 39, wherein a resist pattern for implantation is formed in the thick-film photolithography process.

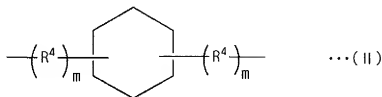
41. **(Canceled)**

42. **(Canceled)**

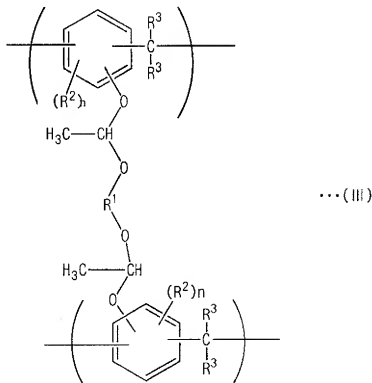
43. **(New)** A method for synthesis of (A) a slightly alkali-soluble or alkali-insoluble novolak resin having a property that solubility in an aqueous alkali solution is enhanced in the presence of an acid, comprising either or both of a constituent unit (a1) represented by the following general formula (I):



wherein R^1 represents either an alkylene group having 1 to 10 carbon atoms which may have a substituent or a group represented by the following general formula (II):

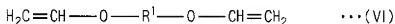


(wherein R^4 represents an alkylene group having 1 to 10 carbon atoms which may have a substituent and m represents 0 or 1), the alkylene group may have an oxygen bond (ether bond) in the main chain, R^2 and R^3 each independently represents a hydrogen atom or an alkyl group having 1 to 3 carbon atoms, and n represents an integer of 1 to 3, and an intermolecular crosslinked moiety (a2) represented by the following general formula (III):



wherein R^1 represents either an alkylene group having 1 to 10 carbon atoms which may have a substituent or a group represented by the above general formula (II) (wherein R^4 represents an alkylene group having 1 to 10 carbon atoms which may have a substituent and m represents 0 or 1), the alkylene group may have an oxygen bond (ether bond) in the main chain, R^2 and R^3 each independently represents hydrogen atom or alkyl group having 1 to 3 carbon atoms, and n represents an integer of 1 to 3,

wherein said method comprises reacting a novolak resin with a crosslinking agent represented by the following general formula (VI):



wherein R^1 represents either an alkylene group having 1 to 10 carbon atoms which may have a substituent or a group represented by the above general formula (II) (wherein R^4 represents an alkylene group having 1 to 10 carbon atoms which may have a substituent and m represents 0 or 1), and the alkylene group may have an oxygen bond (ether bond) in the main chain,

in the substantial absence of an acid catalyst.